

## DESCRIPTION

MULTILAYER WIRING BOARD, MANUFACTURING METHOD THEREOF,  
SEMICONDUCTOR DEVICE, AND WIRELESS ELECTRONIC DEVICE

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## Technical Field

The present invention relates to a multilayer wiring board, a manufacturing method thereof, a semiconductor device in which a semiconductor chip is mounted on the multilayer wiring board, and a wireless electronic device on which the semiconductor device is mounted.

## Background Art

In recent years, with the development of electronic devices, in addition to an improvement of performance of electronic parts, the demand of reductions in size and weight of the electronic parts becomes strict. In particular, in a mobile electronic device typified by a mobile phone, the demand is remarkable in pursuit of the convenience. Against such a background, a multilayer wiring board has been used to efficiently mount a semiconductor chip or a passive device.

Up to now, high-density wiring such as reduction in wiring line width is mainstream. However, in order to reduce the number of parts to be mounted, passive parts typified by capacitors are required to be built in the wiring board.

As a technique that builds a capacitor in a multilayer wiring board, a technique that calcines a high-dielectric